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•	Single-Chip TIA/EIA-232-F Interface for IBM™ PC/AT™ Serial Port	DW PACKAGE (TOP VIEW)
•	Designed to Transmit and Receive 4-μs Pulses (Equivalent to 256 kbit/s)	$V_{DD}\begin{bmatrix} 1 & 20 \\ 1 & 20 \end{bmatrix} V_{CC}$
•	Less Than 21-mW Power Consumption	RA2 3 18 RY2
•	Wide Supply-Voltage Range, 4.75 V to 15 V	RA3 🛛 4 17 🗍 RY3
•	Driver Output Slew Rates Are Internally Controlled to 30 V/μs Max	DY1 [] 5 16] DA1 DY2 [] 6 15] DA2
•	Receiver Input Hysteresis, 1000 mV Typ	RA4 [] 7 14 [] RY4
•	TIA/EIA-232-F Bus-Pin ESD Protection Exceeds: – 15-kV, Human-Body Model – 15-kV IEC1000-4-2 Air Gan	DY3 [8 13] DA3 RA5 [9 12] RY5 V _{SS} [10 11] GND

- Three Drivers and Five Receivers Meet or Exceed the Requirements of TIA/EIA-232-F and ITU V.28
- Complements the SN75LP196

- 8-kV IEC1000-4-2, Contact

- Designed to Replace the Industry-Standard SN75185 and SN75C185 With the Same Flow-Through Pinout
- Packaged in Plastic Small-Outline Package

description

The SN75LP185A is a low-power bipolar device containing three drivers and five receivers with 15 kV of ESD protection on the bus pins with respect to each other. Bus pins are defined as those pins that tie directly to the serial-port connector, including GND. The pinout matches the flow-through design of the industry-standard SN75185 and SN75C185. The flow-through pinout of the SN75LP185A allows easy interconnection of the UART and serial-port connector of the IBM PC/AT and compatibles. The SN75LP185A provides a rugged, low-cost solution for this function with the combination of the bipolar processing and 15 kV of ESD protection.

The SN75LP185A has internal slew-rate control to provide a maximum rate of change in the output signal of 30 V/ μ s. The driver output swing is nominally clamped at \pm 6 V to enable the higher data rates associated with this device and to reduce EMI emissions. Even though the driver outputs are clamped, they can handle voltages up to \pm 15 V without damage. All the logic inputs can accept 3.3-V or 5-V input signals.

The SN75LP185A complies with the requirements of TIA/EIA-232-F and ITU V.28. These standards are for data interchange between a host computer and peripheral at signaling rates up to 20 kbit/s. The switching speeds of the SN75LP185A support rates up to 256 kbit/s.

The SN75LP185A is characterized for operation from 0°C to 70°C.



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Function Tables

DRIVER						
INPUT DA	OUTPUT DY					
Н	L					
L	Н					
Open	L					

RECEIVER

INPUT RA	OUTPUT RY
Н	L
L	Н
Open	Н

logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Positive supply-voltage range (see Note 1	1): V _{CC} V _{CC} (see Note 1)	
Negative supply-voltage range, V_{SS} (see Input-voltage range, V_I : Receiver (RA)	Note 1)	0.5 V to -15 V 30 V to 30 V
Output-voltage range, V_O : Receiver (RY)		-0.5 V to 6 V
Driver (DY) Electrostatic discharge (see Note 2): Bus	pins (human-body model)	
Bus	pins (machine model)	Class 3, B: 500 V
Bus	pins (IEC1000-4-2, contact)	Class 3, D: 15 kV
All p All p	bins (human-body model)	Class 3, A: 5 kV Class 3, B: 400 V
Package thermal impedance, θ_{JA} (see No. Storage temperature range, T_{cta}	ote 3)	
Lead temperature 1,6 mm (1/16 inch) fror	m case for 10 seconds	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to network ground terminal, unless otherwise noted.

2. Per MIL-STD-883 Method 3015.7

3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions

			MIN	NOM	MAX	UNIT
VCC	Supply voltage (see Note 4)		4.75	5	5.25	V
V _{DD}	Supply voltage (see Note 5)		9	12	15	V
VSS	Supply voltage (see Note 5)		-9	-12	-15	V
VIH	High-level input voltage	DA	2			V
VIL	Low-level input voltage	DA			0.8	V
VI	Receiver input voltage	RA	-25		25	V
IOH	High-level output current	RY			-1	mA
IOL	Low-level output current	RY			2	mA
TA	Operating free-air temperature		0		70	°C

NOTES: 4. V_{CC} cannot be greater than V_{DD}.

5. The device operates down to $V_{DD} = V_{CC}$ and $|V_{SS}| = V_{CC}$, but supply currents increase and other parameters may vary slightly from the data-sheet limits.



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supply currents over the recommended operating conditions (unless otherwise noted)

PARAMETER	TEST C	MIN	TYP	MAX	UNIT		
Supply surrent for Versiles	V _{DD} = 9 V,	$V_{SS} = -9 V$			1000		
Supply current for VCC, ICC		V _{DD} = 12 V,	$V_{SS} = -12 V$			1000	
	ent for V _{DD} , I _{DD} No load, All inputs at minimum V _{OH} or maximum V _{OL}	V _{DD} = 9 V,	$V_{SS} = -9 V$			450	
Supply current for VDD, IDD		V _{DD} = 12 V,	$V_{SS} = -12 V$			450	μΑ
		V _{DD} = 9 V,	$V_{SS} = -9 V$			-625	
		V _{DD} = 12 V,	$V_{SS} = -12 V$			-625	

driver electrical characterisitics over the recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS			MIN	TYP†	MAX	UNIT	
Vou	High lovel output veltage	$V_{1L} = 0.8 V,$	V _{DD} = 9 V,	$V_{SS} = -9 V$		5	5.8	6.6	V
VОН	riigh-ievel output voltage	See Figure 1	V _{DD} = 12 V,	$V_{SS} = -12 V,$	See Note 6	5	5.8	6.6	v
Vei		$V_{IH} = 2 V$, $P_{I} = 2 k\Omega$	V _{DD} = 9 V,	$V_{SS} = -9 V$		-5	-5.8	-6.9	V
VOL	Low-level output voltage	See Figure 1	V _{DD} = 12 V,	$V_{SS} = -12 V,$	See Note 6	-5	-5.9	-6.9	v
Чн	High-level input current	V _I at V _{CC}						1	μΑ
۱ _{IL}	Low-level input current	V _I at GND						-1	μA
IOS(H)	Short-circuit high-level output current	V _O = GND or V	SS,	See Figure 2 a	nd Note 7		-30	-55	mA
IOS(L)	Short-circuit low-level output current	V _O = GND or V _I	DD,	See Figure 2 a	nd Note 7		30	55	mA
r _o	Output resistance	$V_{DD} = V_{SS} = V_{SS}$	CC = 0,	V _O = 2 V		300			Ω

NOTES: 6. Maximum output swing is nominally clamped at ±6 V to enable the higher data rates associated with this device and to reduce EMI emissions. The driver outputs may slightly exceed the maximum output voltage over the full V_{CC} and temperature ranges.

7. Not more than one output should be shorted at one time.



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driver switching characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t PHL	Propagation delay time, high- to low-level output	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega, C$	C _L = 15 pF, See Figure 1	300	800	1600	ns
^t PLH	Propagation delay time, low- to high-level output	$R_L = 3 k\Omega$ to 7 kΩ, C	R _L = 3 kΩ to 7 kΩ, C _L = 15 pF, See Figure 1				ns
		V _{CC} = 5 V,	Using V_{TR} = 10%-to-90% transition region, Driver speed = 250 kbit/s, C _L = 15 pF, See Note 8	375		2240	
tтLH	Transition time, low- to high-level output	$V_{DD} = 12 \text{ V},$ $V_{SS} = -12 \text{ V},$ $R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega,$ See Figure 1 and Note 9	Using V _{TR} = \pm 3 V transition region, Driver speed = 250 kbit/s, C _L = 15 pF	200		1500	ns
			Using $V_{TR} = \pm 2 V$ transition region, Driver speed = 250 kbit/s, $C_L = 15 pF$	133		1000	
			Using V _{TR} = \pm 3 V transition region, Driver speed = 125 kbit/s, C _L = 2500 pF			2750	
		V _{CC} = 5 V,	Using VTR = 10%-to-90% transition region, Driver speed = 250 kbit/s, C_L = 15 pF, See Note 8	375		2240	
t _{THL}	Transition time, high- to low-level output $V_{DD} = 12$ $V_{SS} = -1$ $R_L = 3 kG$ See Figur Note 9	$V_{DD} = 12 V,$ $V_{SS} = -12 V,$	Using V _{TR} = \pm 3 V transition region, Driver speed = 250 kbit/s, C _L = 15 pF	200		1500	ns
		$R_L = 3 \text{ kg} \text{ to } 7 \text{ kg},$ See Figure 1 and Note 9	Using V _{TR} = \pm 2 V transition region, Driver speed = 250 kbit/s, C _L = 15 pF	133		1000	
			Using V _{TR} = \pm 3 V transition region, Driver speed = 125 kbit/s, C _L = 2500 pF			2750	
SR	Output slew rate	V _{CC} = 5 V, V _{DD} = 12 V, V _{SS} = -12 V	Using V _{TR} = ± 3 V transition region, Driver speed = 0 to 250 kbit/s, C _L = 15 pF	4	20	30	V/us

NOTES: 8. Equivalent to the SN75C185. The SN75LP185A output-voltage swing is clamped to about 70% of the typical SN75C185 output-voltage swing, and the specified limits reflect the reduced output swing.

9. Maximum output swing is limited to ±6 V to enable the higher data rates associated with this device and to reduce EMI emissions.

receiver electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
V _{IT+}	Positive-going input threshold voltage	See Figure 3		1.6	2	2.55	V
V _{IT}	Negative-going input threshold voltage	See Figure 3		0.6	1	1.45	V
V _{HYS}	Input hysteresis, V _{IT+} V _{IT-}	See Figure 3		600	1000		mV
VOH	High-level output voltage	I _{OH} = -1 mA		2.5	3.9		V
VOL	Low-level output voltage	I _{OL} = 2 mA			0.33	0.5	V
	High lovel input ourrept	$V_{I} = 3 V$		0.43	0.6	1	~^^
HI IH	High-level liput current	V _I = 25 V		3.6	5.1	8.3	IIIA
	Low lovel input current	$V_{I} = -3 V$		-0.43	-0.6	-1	~^^
'IL	Low-level input current	V _I = -25 V		-3.6	-5.1	-8.3	IIIA
IOS(H)	Short-circuit high-level output current	$V_{O} = 0$, See Figure 5 and I	Note 7			-20	mA
IOS(L)	Short-circuit low-level output current	$V_{O} = V_{CC}$, See Figure 5 and I	Note 7			20	mA
R _{IN}	Input resistance	$V_{I} = \pm 3 V \text{ to } \pm 25 V$		3	5	7	kΩ

NOTE 7: Not more than one output should be shorted at one time.



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receiver switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 4)

	PARAMETER	MIN	TYP	MAX	UNIT
^t PHL	Propagation delay time, high- to low-level output		400	900	ns
^t PLH	Propagation delay time, low- to high-level output		400	900	ns
^t TLH	Transition time, low- to high-level output		200	500	ns
^t THL	Transition time, high- to low-level output		200	400	ns
tSK(p)	Pulse skew tpLH tpHL		200	425	ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. The pulse generator has the following characteristics: For C_L < 1000 pF: t_W = 4 μ s, PRR = 250 kbit/s, Z_O = 50 Ω , t_r = t_f < 50 ns. For C_L = 2500 pF: t_W = 8 μ s, PRR = 125 kbit/s, Z_O = 50 Ω , t_r = t_f < 50 ns. B. C_L includes probe and jig capacitance.

Figure 1. Driver Parameter Test Circuit and Waveform







Figure 3. Receiver V_{IT} Test



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PARAMETER MEASUREMENT INFORMATION



NOTES: A. The pulse generator has the following characteristics: $t_W = 4 \mu s$, PRR = 250 kbit/s, $Z_O = 50 \Omega$, $t_r = t_f < 50 ns$. B. CL includes probe and jig capacitance.

Figure 4. Receiver Parameter Test Circuit and Waveform



Figure 5. Receiver I_{OS} Test

APPLICATION INFORMATION

Diodes placed in series with the V_{DD} and V_{SS} leads protect the SN75LP185A in the fault condition when the device outputs are shorted to ± 15 V and the power supplies are at low voltage and provide low-impedance paths to ground (see Figure 6).



Figure 6. Power-Supply Protection to Meet Power-Off Fault Conditions of TIA/EIA-232-F



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